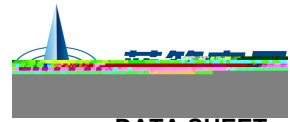


BRBC846Q

Rev.A Apr.-2022



DATA SHEET

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F 2017

/ Descriptions

SOT-23 NPN

Silicon NPN transistor in a SOT-23 Plastic Package.

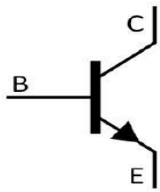
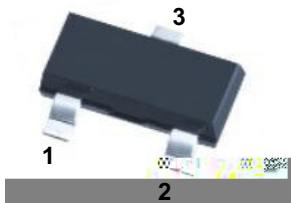
/ Features

AEC-Q101

Low current, Low voltage, Qualified to AEC-Q101 Standards for High Reliability, HF Product.

/ Applications

General power amplifier and switching application, Meet the stringent requirements of automotive applications.

/ Equivalent Circuit**/ Pinning**

PIN1 Base PIN 2 Emitter PIN 3 Collector

/ h_{FE} Classifications & Marking

h_{FE} Classifications Symbol	A	B
h_{FE} Range	110~220	200~450
Marking	1AQ	Q1B

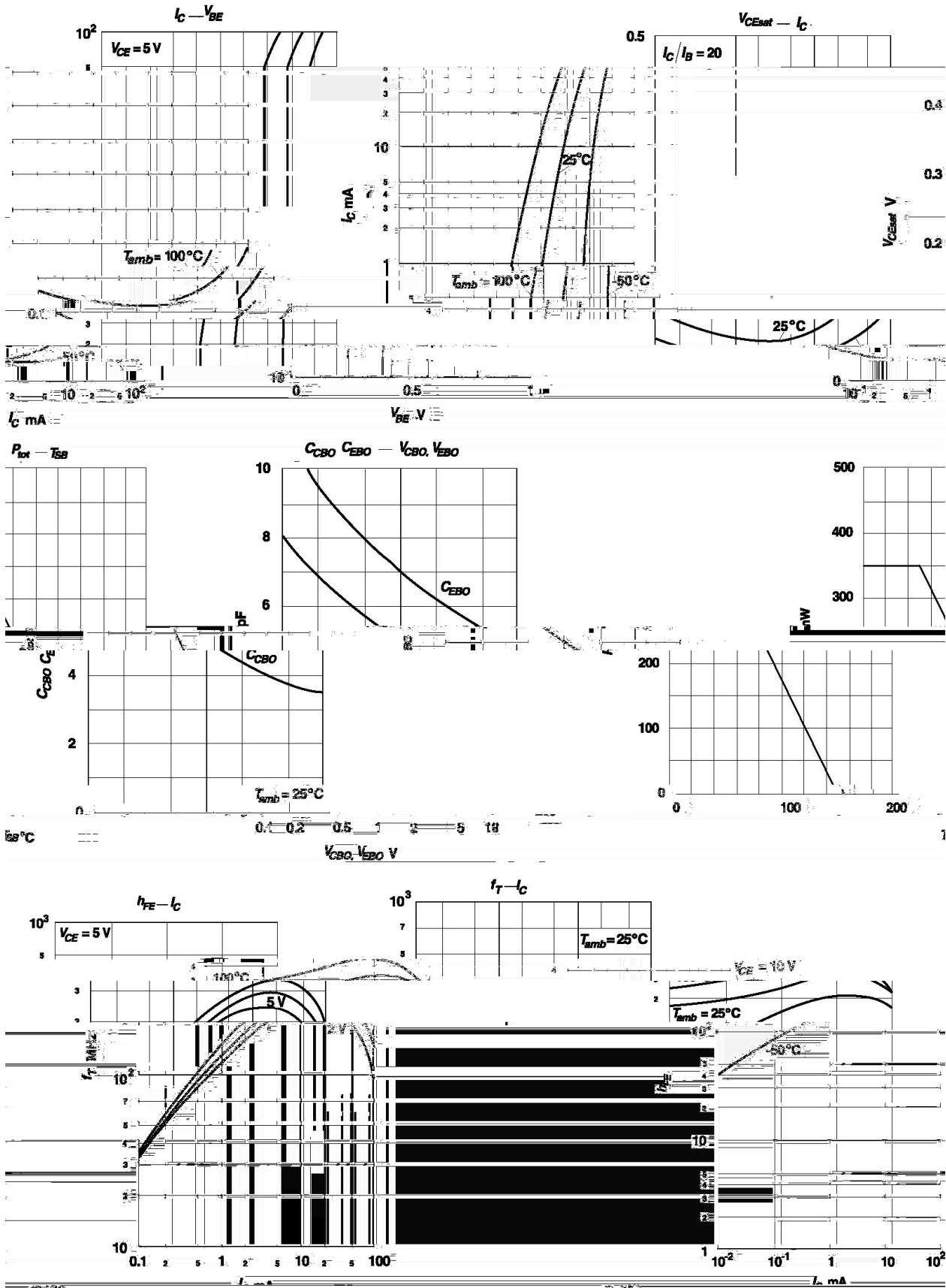
/ Absolute Maximum Ratings(Ta=25)

Parameter	Symbol	Rating	Unit
Collector to Base Voltage	V_{CBO}	80	V
Collector to Emitter Voltage	V_{CEO}	65	V
Emitter to Base Voltage	V_{EBO}	6.0	V
Collector Current - Continuous	I_C	100	mA
Collector Power Dissipation	P_C	350	mW
Junction Temperature	T_j	150	°C
Storage Temperature Range	T_{stg}	-55 150	°C

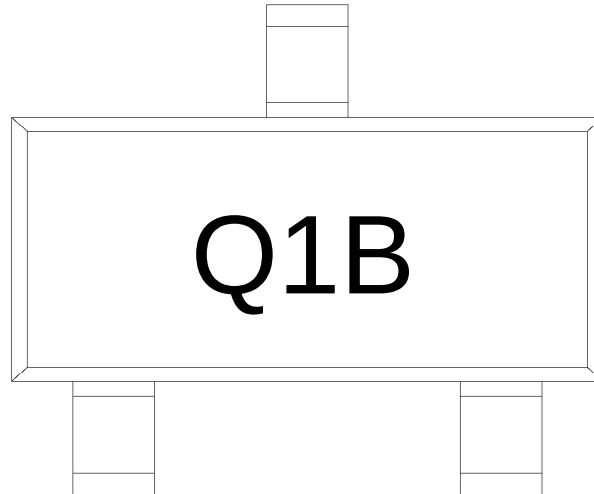
/ Electrical Characteristics(Ta=25)

Parameter	Symbol	Test Conditions	Min	Typ	Max	Unit
Collector Cut-Off Current	I_{CBO}	$V_{CB}=30V$ $I_E=0$			0.015	μA
DC Current Gain	h_{FE}	$V_{CE}=5.0V$ $I_C=2.0mA$	110		450	
Collector to Emitter Saturation Voltage	$V_{CE(sat)(1)}$	$I_C=10mA$ $I_B=0.5mA$		0.09	0.25	V
	$V_{CE(sat)(2)}$	$I_C=100mA$ $I_B=5.0mA$		0.2	0.6	V
Base to Emitter Saturation Voltage	$V_{BE(sat)(1)}$	$I_C=10mA$ $I_B=0.5mA$		0.7		V
	$V_{BE(sat)(2)}$	$I_C=100mA$ $I_B=5.0mA$		0.9		V
Base to Emitter Voltage	$V_{BE(1)}$	$V_{CE}=5.0V$ $I_C=2.0mA$	0.58		0.7	V
	$V_{BE(2)}$	$V_{CE}=5.0V$ $I_C=10mA$			0.75	V
Transition Frequency	f_T	$V_{CE}=5.0V$ $f=100MHz$ $I_C=10mA$		300		MHz
Collector Output Capacitance	C_{ob}	$V_{CB}=10V$ $f=1.0MHz$ $I_E=0$		2.5	4.5	pF
Noise Figure	NF	$V_{CE}=6.0V$ $I_C=0.1mA$ $R_g=10K\Omega$ $f=1.0KHz$		1.0	10	dB

/ Electrical Characteristic Curve



/ Marking Instructions



Q

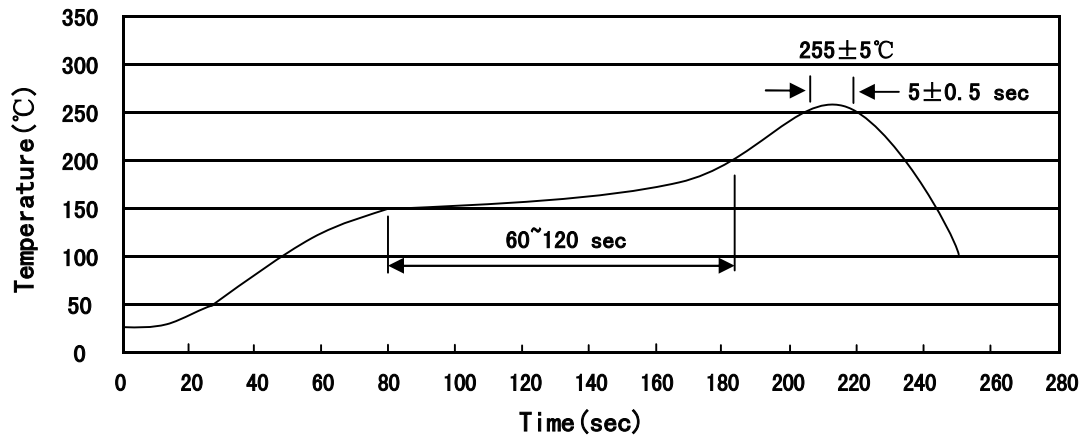
1B

Note:

Q: Automobile halogen-free product Code

1B: Product Type Code

() / Temperature Profile for IR Reflow Soldering(Pb-Free)



说明：

- 1、预热温度 150~200°C，时间 60~120sec;
- 2、峰值温度 255±5°C，时间持续为 5±0.5sec;
- 3、焊接制程冷却速度为 2~10°C/sec.

Note:

- 1.Preheating:150~200°C, Time:60~120sec.
- 2.Peak Temp.:255±5°C, Duration:5±0.5sec.
3. Cooling Speed: 2~10°C/sec.

/ Resistance to Soldering Heat Test Conditions

温度：260±5°C

时间：10±1 sec.

Temp.:260±5°C

Time:10±1 sec

/ Packaging SPEC.

卷盘包装 / REEL

Package Type 封装形式	Units 包装数量					Dimension 包装尺寸 (unit: mm ³)		
	Units/Reel 只/卷盘	Reels/Inner Box 卷盘/盒	Units/Inner Box 只/盒	Inner Boxes/Outer Box 盒/箱	Units/Outer Box 只/箱	Reel	Inner Box 盒	Outer Box 箱
SOT-23	3,000	10	30,000	6	180,000	7" ×8	180×120×180	390×385×205

/ Notices